



PRODUCT DATA SHEET



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Datasheet



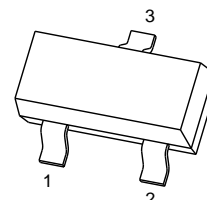
Resources



Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
-50V	8Ω@-10V	-0.13A
	10Ω@-5V	



1. GATE
2. SOURCE
3. DRAIN

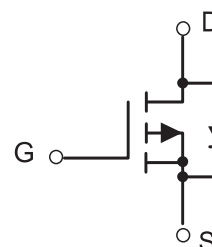
SOT-23

FEATURE

- Energy Efficient
- Low Threshold Voltage
- High-speed Switching
- Miniature Surface Mount Package Saves Board Space

APPLICATION

- DC-DC converters, load switching, power management in portable and battery-powered products such as computers, printers, cellular and cordless telephones.



MAXIMUM RATINGS ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-50	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	-0.13	A
Pulsed Drain Current (note 1) @ $t_p < 10 \mu s$	I_{DM}	-0.52	A
Power Dissipation	P_D	225	mW
Thermal Resistance from Junction to Ambient (note 2)	$R_{\theta JA}$	556	$^{\circ}\text{C/W}$
Junction Temperature	T_J	125	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^{\circ}\text{C}$
Maximum Lead Temperature for Soldering Purposes , Duration for 5 Seconds	T_L	260	$^{\circ}\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS $T_a=25^\circ\text{C}$ unless otherwise specified

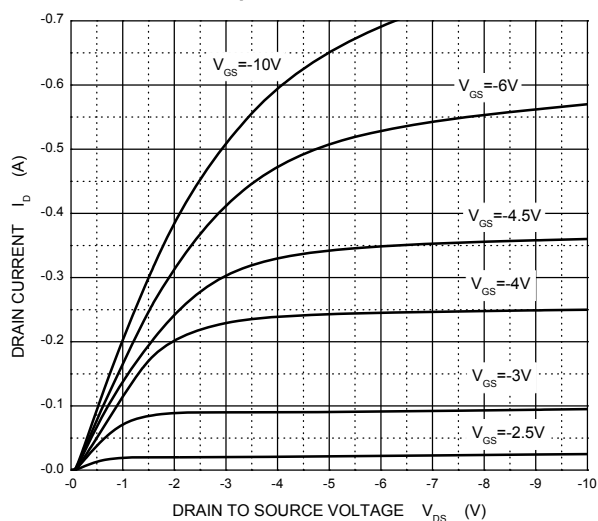
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-50			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -50V, V _{GS} = 0V			-15	μA
		V _{DS} = -25V, V _{GS} = 0V			-0.1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±5	μA
Gate threshold voltage (note 3)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.9	-1.6	-2	V
Drain-source on-resistance (note 3)	R _{DS(on)}	V _{GS} = -5V, I _D = -0.1A		5.8	10	Ω
		V _{GS} = -10V, I _D = -0.1A		4.5	8	Ω
Forward transconductance (note 1)	g _{FS}	V _{DS} = -25V; I _D = -100mA	50			mS
DYNAMIC CHARACTERISTICS (note 4)						
Input capacitance	C _{iss}	V _{DS} = 5V, V _{GS} = 0V, f = 1MHz		30		pF
Output capacitance	C _{oss}			10		pF
Reverse transfer capacitance	C _{rss}			5		pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time	t _{d(on)}	V _{DD} = -15V, R _L = 50Ω, I _D = -2.5A		2.5		ns
Turn-on rise time	t _r			1		ns
Turn-off delay time	t _{d(off)}			16		ns
Turn-off fall time	t _f			8		ns
SOURCE-DRAIN DIODE CHARACTERISTICS						
Continuous Current	I _S				-0.13	A
Pulsed Current	I _{SM}				-0.52	A
Diode forward voltage (note 3)	V _{SD}	I _S = -0.13A, V _{GS} = 0V			-2.2	V

Notes :

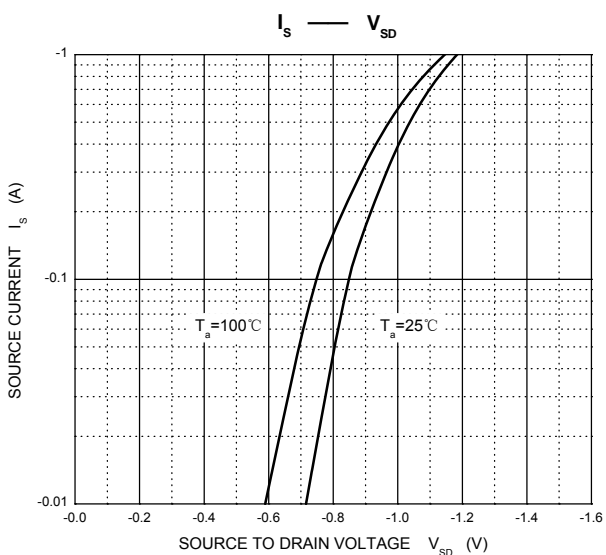
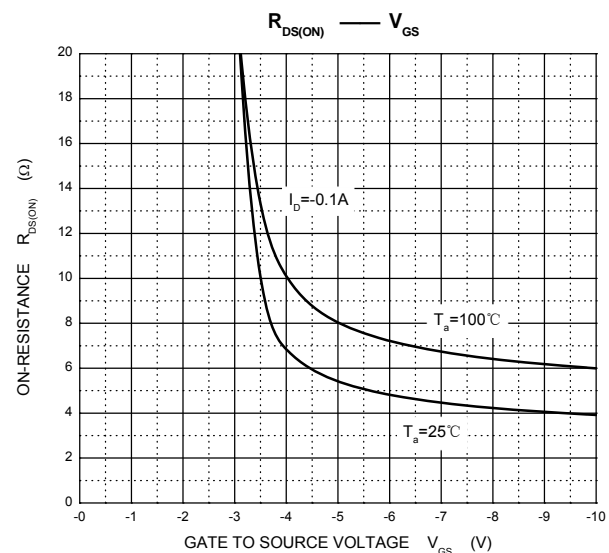
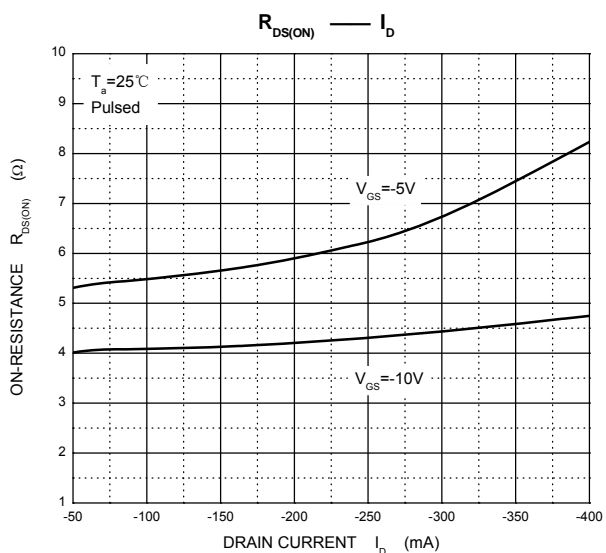
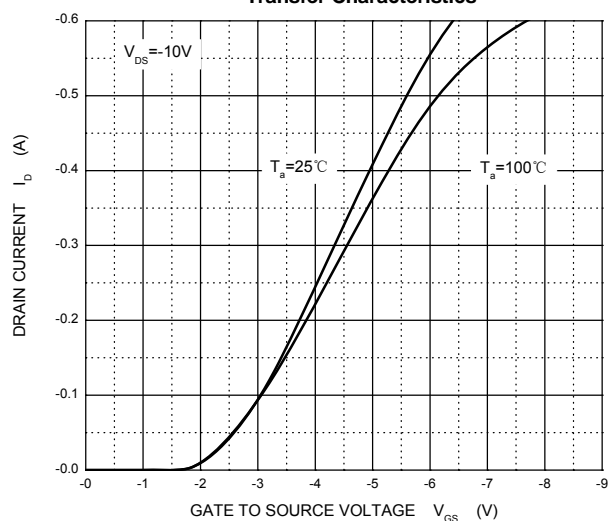
1. Repetitive rating : Pulse width limited by junction temperature.
2. Surface mounted on FR4 board , $t \leq 10s$.
3. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to producing.

Typical Characteristics

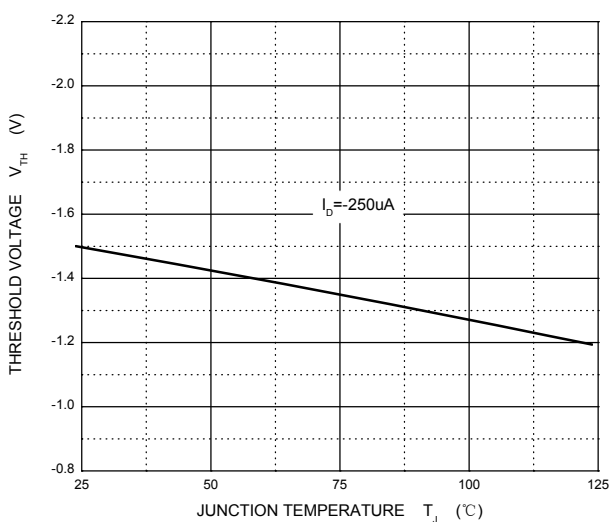
Output Characteristics



Transfer Characteristics



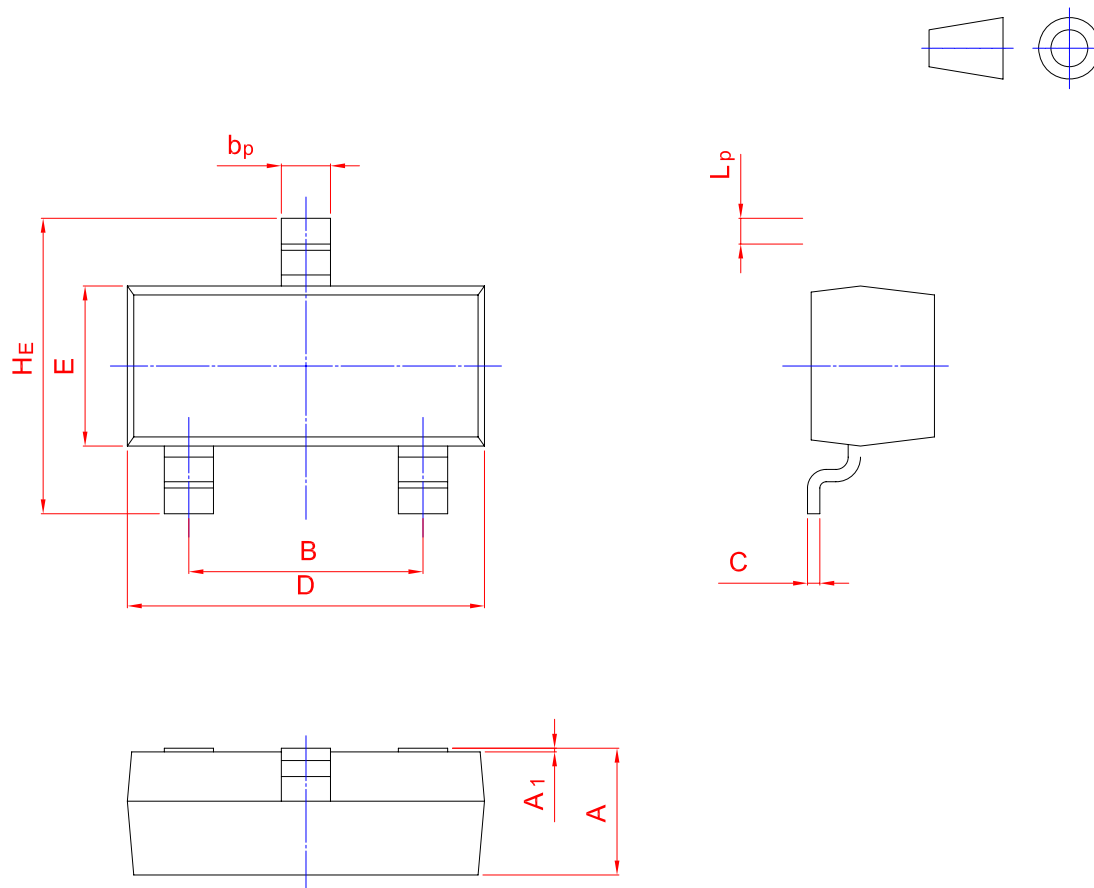
Threshold Voltage



PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT-23



UNIT	A	B	b _p	C	D	E	H _E	A ₁	L _p
mm	1.40 0.95	2.04 1.78	0.50 0.35	0.19 0.08	3.10 2.70	1.65 1.20	3.00 2.20	0.100 0.013	0.50 0.20

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